

RD Number: RD089

RD Title: TB6605FTG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	IC1	1	TB6605FTG	TB6605FTG	TOSHIBA	Motor Driver IC	QFN36	
2	R1	1	3.9kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
3	R1A	1	3.9kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
4	R1B	1	3.9kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
5	R2	1	100Ω 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
6	R3	1	68kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
7	R4	1	33kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
8	R5	1	1kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
9	R6	1	0.1Ω 1W	—	—	Fixed Metal Film Resistor	9.0mm×3.0mm	
10	R7	1	10kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
11	R8	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
12	R9	0	Not mount	—	—	Chip resistor	3.2mm×1.6mm	✓
13	R10	1	100kΩ 0.25W	—	—	Chip resistor	3.2mm×1.6mm	
14	R11	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
15	R12	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
16	R13	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
17	R14	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
18	R15	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
19	R16	1	0Ω	—	—	Chip resistor	3.2mm×1.6mm	
20	R17	1	11kΩ 0.125W	—	—	Chip resistor	1.6mm×0.8mm	
21	C1	1	0.01μF 50V	—	—	Chip capacitor	1.6mm×0.8mm	
22	C2	1	0.01μF 50V	—	—	Chip capacitor	1.6mm×0.8mm	
23	C3	1	0.01μF 50V	—	—	Chip capacitor	1.6mm×0.8mm	
24	C4	1	0.015μF 50V	—	—	Chip capacitor	1.6mm×0.8mm	
25	C5	1	1.0μF 50V	—	—	Chip capacitor	2.0mm×1.25mm	



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